

EVG's Process Services

EVG process engineering provides full service wafer processing.

Our experienced team of process, application and equipment engineers supports samples processing, design of experiments and process optimization.

EVG's application labs provide the industry's most advanced equipment in class 10 environments with a professional setting and infrastructure for wafer processing.

Benefits

- Processing by leading experts
- No capital expenditure required
- Access to state-of-the-art equipment
- Small batch sizes possible
- Capability to process wafers from 2" to 300 mm
- High success rate for sample processing
- Reliable scheduling and fast execution
- Access to EVG's partner service providers
- All EVG unit operations can be utilized in any lab



Cleanroom at EVG headquarters



www.EVGroup.com



Global Locations Application Laboratories

Headquarters

EV Group
E. Thallner GmbH
DI Erich Thallner Strasse 1
4782 St. Florian am Inn
Phone: +43 7712 5311 0
Fax: +43 7712 5311 4600
E-Mail: ProcessTechnologySD@EVGroup.com

Japan

EV Group Japan KK
Yokohama Business Park East Tower 1F
134, Godo-cho, Hodogaya-ku,
Yokohama-shi, Kanagawa, 240-0005
Phone: +81 45 348 0665
Fax: +81 45 348 0666
E-Mail: Technology@EVGroup.jp

North America

EV Group Inc.
7700 South River Parkway
Tempe, AZ 85284
Phone: +1 480 305 2400
Fax: +1 480 305 2401
E-Mail: ProcessUS@EVGroup.com

© EV Group (EVG). All rights reserved. V18/01

Data, design and specifications may not simultaneously apply; or depend on individual equipment configuration, process conditions and materials and may vary accordingly. EVG reserves the right to change data, design and specifications without prior notice.

All trademarks, logos, website addresses or equipment names that contain the letters or words "EVG" or "EV Group" or any combination thereof, as well as the following names and acronyms are registered trademarks and/or the property of EV Group: ComBond®, CoverSpin™, EZB®, EZ Bond®, EZD®, EZ Debond®, EZR®, EZ Release®, GEMINI®, HERCULES®, HyperIntegration®, IQ Aligner®, LowTemp™, NanoAlign®, NanoFill™, NanoSpray™, NIL-COM®, NILPhotonics®, OmniSpray®, SmartEdge®, SmartNIL®, SmartView®, The Triple "i" Company, Invent-Innovate-Implement®, Triple i®. Other product and company names may be registered trademarks of their respective owners.

Printed on paper from sustainable sources



Process Services

Superior process expertise...
...Every step of the way

EVG at a glance

Our comprehensive process knowledge is a result of our decades of experience. This knowledge creates benefits and advantages for our customers from the early stages of process development to the final goal of high volume production.

With state-of-the-art application labs at our headquarters in Austria, along with the United States and Japan, EV Group is focused on delivering superior process expertise to our growing global customer base every step of the way. We can provide support for initial development through final integration at the customer's site.

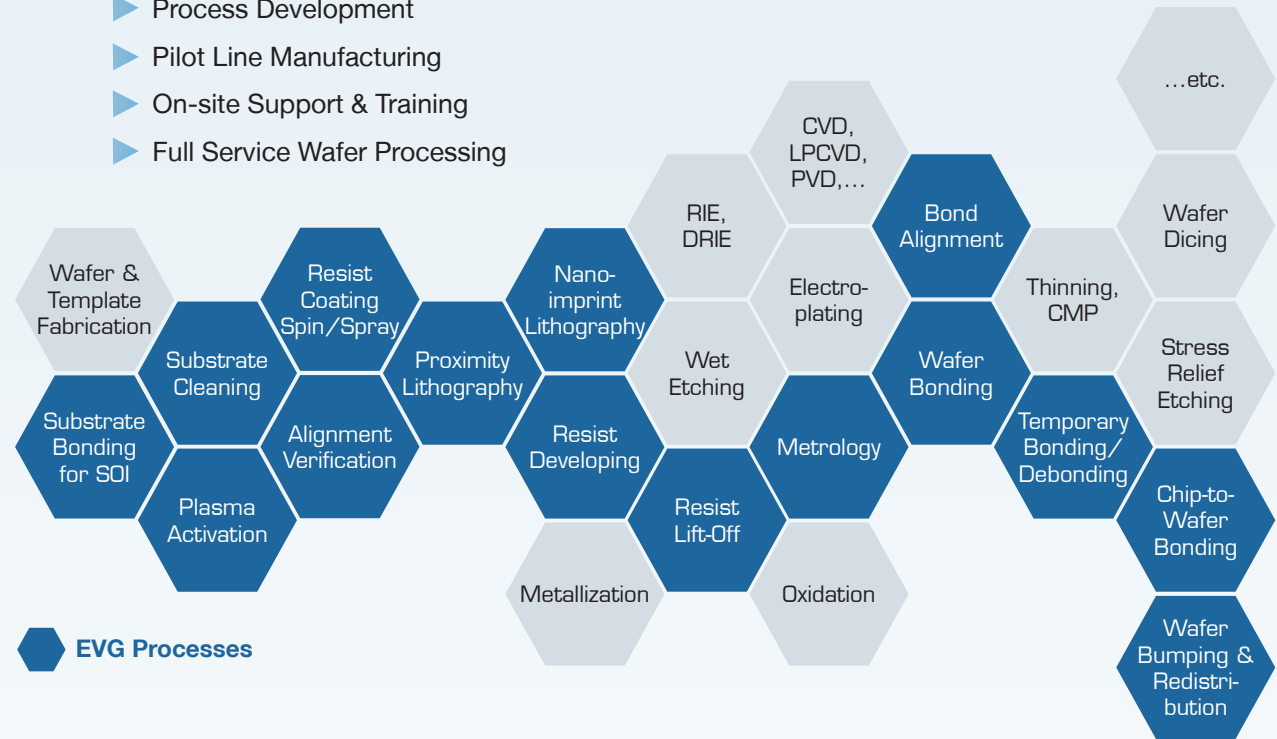
Process know-how is key in achieving the shortest time to market for your product. EV Group is a global supplier to:

- Advanced Packaging & 3D Interconnect
- MEMS
- SOI & Engineered Substrates
- Compound Semiconductor and Silicon Based Power Devices
- Nanotechnology



EVG Process Expertise

- ▶ Proof of Concept
- ▶ Process Development
- ▶ Pilot Line Manufacturing
- ▶ On-site Support & Training
- ▶ Full Service Wafer Processing



EVG's worldwide application labs focus on demonstrating and developing processes within our core competencies of wafer bonding, lithography and metrology. We provide access to other key processing steps through our preferred partner network around the globe. Please contact us and let EVG be your total process service solution provider.

